# **Small Signal Diodes**

# MMBD1201 - MMBD1205

#### Features

• These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### ABSOLUTE MAXIMUM RATINGS (Note 1, Note 2)

Values are at  $T_A = 25^{\circ}C$  unless otherwise noted.

Symbol	Paramete	Value	Unit	
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage		100	V
I <sub>F(AV)</sub>	Average Rectified Forwa	200	mA	
I <sub>FSM</sub>	Non-Repetitive Peak Forward Surge Current	Pulse Width = 1.0 s	1.0	A
	ourient	Pulse Width = 1.0 μs	2.0	
T <sub>STG</sub>	Storage Temperature Range		-55 to + 150	°C
TJ	Operating Junction Temperature		150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. These ratings are based on a maximum junction temperature of 150°C.

2. These are steady-state limits. ON Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

#### THERMAL CHARACTERISTICS

Values are at  $T_A = 25^{\circ}C$  unless otherwise noted.

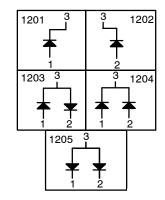
Symbol	Parameter	Value	Unit
PD	Power Dissipation	350	mW
	Derate Above 25°C	2.8	mW/°C
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient	357	°C/W



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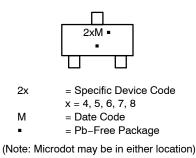
#### **CONNECTION DIAGRAM**





SOT-23 CASE 318-08

#### MARKING DIAGRAM



#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBD1201, MMBD1202, MMBD1203, MMBD1204, MMBD1205	SOT-23 (Pb-Free Halide Free)	3000 / Tape & Reel

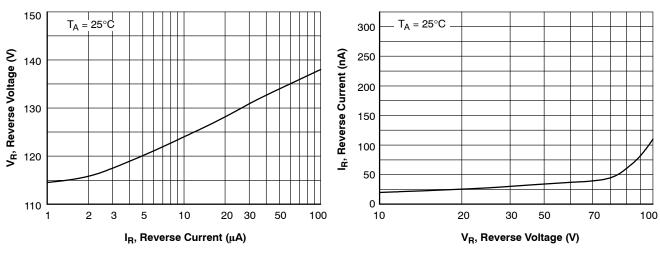
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## MMBD1201 - MMBD1205

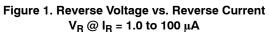
Symbol	Parameter	Conditions	Min.	Max.	Unit
V <sub>R</sub>	Breakdown Voltage	I <sub>R</sub> = 100 μA	100	-	V
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 1.0 mA	550	600	mV
		I <sub>F</sub> = 10 mA	660	740	mV
		I <sub>F</sub> = 100 mA	820	920	mV
		I <sub>F</sub> = 200 mA	0.87	1.0	V
		I <sub>F</sub> = 300 mA	-	1.1	V
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 20 V	-	25	nA
		V <sub>R</sub> = 50 V	-	50	nA
		V <sub>R</sub> = 50 V, T <sub>A</sub> = 150°C	-	100	μA
C <sub>T</sub>	Total Capacitance	V <sub>R</sub> = 0 V, f = 1.0 MHz	-	2.0	pF
t <sub>rr</sub>	Reverse Recovery Time	$I_{F} = I_{R} = 10 \text{ mA}, I_{RR} = 1.0 \text{ mA}, \\ R_{L} = 100 \Omega$	-	4.0	ns

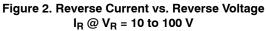
#### **ELECTRICAL CHARACTERISTICS** Values are at $T_A = 25^{\circ}C$ unless otherwise noted.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



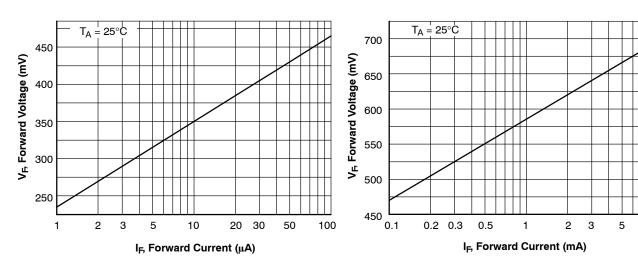
### **TYPICAL PERFORMANCE CHARACTERISTICS**



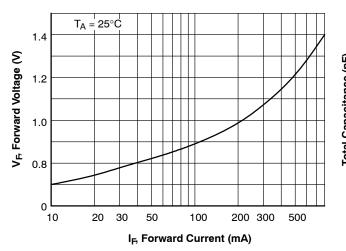


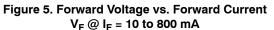
## MMBD1201 - MMBD1205

#### TYPICAL PERFORMANCE CHARACTERISTICS (continued)









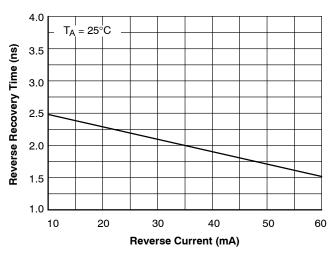




Figure 4. Forward Voltage vs. Forward Current  $V_F @ I_F = 0.1$  to 10 mA

10

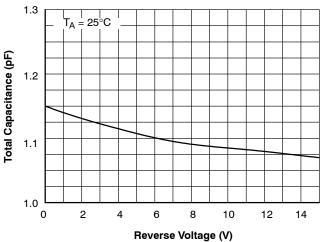
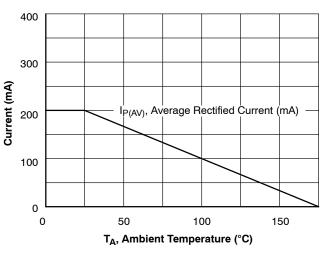
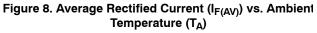


Figure 6. Total Capacitance vs. Reverse Voltage





### MMBD1201 - MMBD1205

# TYPICAL PERFORMANCE CHARACTERISTICS (continued)

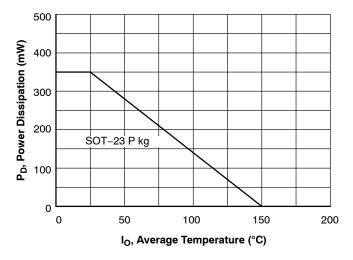


Figure 9. Power Derating Curve

#### MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

D

3

TOP VIEW

SIDE VIEW

Нe

DETAIL A

-3X b

# onsemi



SCALE 4:1

A\_\_\_\_ ' A1SOT-23 (TO-236) CASE 318 ISSUE AT

0.25

-L1

DETAIL A

END VIEW

DATE 01 MAR 2023

NDTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
с	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10*	0*		10*





XXX = Specific Device Code

M = Date Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

#### **STYLES ON PAGE 2**

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# MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

# onsemi

#### SOT-23 (TO-236) CASE 318 ISSUE AT

#### DATE 01 MAR 2023

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE		
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE	2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE	3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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